

DIGITAL IMAGING @ PRODUCTION SPEEDS™

# Maskless

## LITHOGRAPHY

DIGITAL IMAGING AT PRODUCTION SPEEDS™

### MLI-3000™ SERIES

#### Direct Digital Imaging Systems

##### FEATURES

**Highest Throughput in the PCB Industry with Standard Resists**  
Controlled material costs and availability.

##### Next Generation Digital Printer

MLI's Direct Digital Imaging Systems are powered by a patented, breakthrough Gray Level Imaging technology (GLI) which provides unprecedented print speeds on standard resists.

##### Best in Class Side-to-Side Registration

MLI's Direct Digital Imaging Systems utilize a patented "hole free" alignment technology producing superior side-to-side registration accuracy.

##### Fastest ROI in the Industry

MLI's Direct Digital Imaging Systems have the fastest ROI of any competitive digital imaging system on the market.

##### No Clean Room Required

MLI's Direct Digital Imaging Systems are not affected by volatile organics so no special room with hydrocarbon-free filtration, etc. is required.

##### Flexible Alignment on Tight Tolerance Boards

The MLI digital technology provides precision measurement and advanced scaling so that layer patterns can be precisely registered to compensate for material distortions and thus minimize this source of yield loss.

##### Fits Easily in Existing Fabs

The system is the size of a small contact printer and can be operated in your existing photolithography clean room and no water cooling, no ancillary support equipment required.

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### MLI-3000™ SERIES

#### Specifications

##### MLI 3000 series

|                                    |   |
|------------------------------------|---|
| <i>Minimum Feature Size</i>        | 50 $\mu$ m                                  |
| <i>Resolution</i>                  | 5 $\mu$ m                                   |
| <i>Edge Roughness</i>              | $\pm$ 2.5 $\mu$ m                           |
| <i>Light Source</i>                | Mercury arc lamps                           |
| <i>Registration Accuracy</i>       | $\pm$ 12.5 $\mu$ m                          |
| <i>Tact Time</i>                   | 20sec / panel (with scaling)                |
| <i>Side-to-Side Registration</i>   | 12.5 $\mu$ m                                |
| <i>Maximum Substrate Size</i>      | 26.2" $\times$ 32.1" (665mm $\times$ 815mm) |
| <i>Maximum Exposure Area</i>       | 26" $\times$ 32" (660mm $\times$ 813mm)     |
| <i>Maximum Substrate Thickness</i> | 0.315" (8.0mm)                              |
| <i>Average Data Prep. Time</i>     | 12 seconds / panel                          |

##### Applications

- Inner layers
- Outer layers
- Sequential build-up
- Flex and Rigid Flex PCBs
- MEMS

##### Standard Configuration

- Dynamic registration
- Real-time local scaling
- ODD ++ and Gerber input
- Hole-free inner layer registration
- Serialization and alphanumeric
- Internal vacuum system
- Internal HEPA filter

